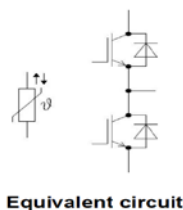


High Speed IGBT in Trench and Fieldstop Technology



Features:

- 1200V 450A, $V_{CE(sat)} = 2.1V @ 25^{\circ}C$
- High RBSOA capability
- Trench/FS technology
- Low reverse-recovery losses
- High SC capability

Applications:

- Motor drives
- Solar applications
- UPS systems
- Commercial electric vehicles
- Three-level applications

Mechanical Features:

- High power and thermal cycling capability
- Maximum junction temperature $175^{\circ}C$
- High power density
- PressFIT contact technology
- Isolated base plate

Key Performance and Package Parameters

Type	V_{CES}	I_{Cnom}	$V_{CESat}, T_{vj}=25^{\circ}C$	T_{vjmax}	Marking
PM450T2120HS1	1200V	450A	2.1V	$175^{\circ}C$	PM450T2120HS1

IGBT Inverter

Maximum Rated Values at $T_{vj}=25^{\circ}C$ (unless otherwise specified)

Parameter	Symbols	Value	Units
Collector-emitter voltage	V_{CES}	1200	V
Continuous DC collector current $T_c = 100^{\circ}C$	I_C	450	A
Pulsed collector current Note *1	I_{CP}	900	A
Diode forward current	I_F	450	A
Gate-emitter peak voltage	V_{GES}	± 30	V
Repetitive peak forward current	I_{FRM}	900	A
Operating junction temperature	T_{vj}	$-40 \sim +150$	$^{\circ}C$
Storage temperature	T_{stg}	$-40 \sim +125$	$^{\circ}C$

Note *1 : Pulse width limited by T_{vjmax} .

IGBT, Inverter

Characteristic Values at $T_{vj}=25^{\circ}\text{C}$ (unless otherwise specified)

Parameter	Symbols	Conditions	Value			Unit		
			Min	Typ	Max			
Collector-emitter saturation voltage	V _{CEsat}	I _C =450A, V _{GE} =15V, T _{vj} =25°C I _C =450A, V _{GE} =15V, T _{vj} =125°C I _C =450A, V _{GE} =15V, T _{vj} =150°C	- - -	2.1 2.49 2.58	2.6 - -	V		
Gate-emitter threshold voltage	V _{GE(th)}	I _C =9.8mA, V _{CE} =V _{GE} , T _{vj} =25°C	5.7	6.2	6.7	V		
Internal gate resistor	R _{Gint}	T _{vj} =25°C	-	1.4	-	Ω		
Collector-emitter leakage current	I _{CES}	V _{CE} =1200V, V _{GE} =0V, T _{vj} =25°C	-	-	200	uA		
Gate-emitter leakage current	I _{GES}	V _{CE} =0V, V=20V T _{vj} =25°C	-	-	±300	nA		
Input capacitance	C _{ies}	f=1MHz, V _{CE} =25V, V _{GE} =0V	-	106	-	nF		
Reverse transfer capacitance	C _{res}	f=1MHz, V _{CE} =25V, V _{GE} =0V	-	880	-	pF		
Gate charge	Q _G	V _{CC} = 600V, V _{GE} = 15V	-	2270	-	nC		
Turn-on delay time, Inductive load	t _{d(on)}	V _{CC} =600V I _C =450A V _{GE} =15V R _G =20Ω	T _{vj} =25°C T _{vj} =125°C T _{vj} =150°C	- - -	1.09 0.99 0.99	- - -	μs	
Rise time, inductive load	t _r		T _{vj} =25°C T _{vj} =125°C T _{vj} =150°C	- - -	0.50 0.51 0.52	- - -	μs	
Turn-off delay time,inductive load	t _{d(off)}		T _{vj} =25°C T _{vj} =125°C T _{vj} =150°C	- - -	1.48 1.57 1.59	- - -	μs	
Fall time, inductive load	t _f		T _{vj} =25°C T _{vj} =125°C T _{vj} =150°C	- - -	0.11 0.11 0.12	- - -	μs	
Turn-on switching Loss	E _{on}		T _{vj} =25°C T _{vj} =125°C T _{vj} =150°C	- - -	132.49 161.69 169.26	- - -	mJ	
Turn-off switching loss	E _{off}		T _{vj} =25°C T _{vj} =125°C T _{vj} =150°C	- - -	59.69 66.74 67.86	- - -	mJ	
SC data	I _{SC}		V _{CC} = 600V R _G = 20Ω V _{GE} ≤ 15V V _{CE} max=V _{CE} -L _{SCE} *di/dt	t _p ≤ 10μs T _{vj} =150°C	-	1800	-	A

Thermal resistance

Parameter	Symbols	Value			Units
		Min	Typ	Max	
Thermal resistance, per IGBT junction to case	$R_{th(j-c)}$	-	-	0.09	K/W
Thermal resistance, per diodes junction to case	$R_{th(j-c)}$	-	-	0.14	

Diode Inverter (unless otherwise specified)

Parameter	Symbols	Conditions	Value			Unit
			Min	Typ	Max	
Forward voltage	V_F	$I_F=450A, V_{GE}=0V$	$T_{vj}=25^{\circ}C$	-	1.90	-
			$T_{vj}=125^{\circ}C$	-	1.60	-
			$T_{vj}=150^{\circ}C$	-	1.54	-
Recovery charge	Q_r	$I_F=450A, V_R=600V$ $-di_F/dt=1000A/\mu s,$ $V_{GE}=-15V$	$T_{vj}=25^{\circ}C$	-	10.90	-
			$T_{vj}=125^{\circ}C$	-	41.77	-
			$T_{vj}=150^{\circ}C$	-	52.48	-
Reverse recovery energy	E_{rec}	$I_F=450A, V_R=600V$ $-di_F/dt=1000A/\mu s$ $V_{GE}=-15V$	$T_{vj}=25^{\circ}C$	-	4.57	-
			$T_{vj}=125^{\circ}C$	-	10.98	-
			$T_{vj}=150^{\circ}C$	-	13.65	-

Module

Parameter	Symbols	Conditions	Value			Unit
Isolation voltage	V_{ISOL}	$f=50Hz, t=1min, RMS$	-	2700	-	V
Material of module base plat			-	Cu	-	
Internal isolation			-	Al_2O_3	-	
Creepage distance	d_{Creep}	Terminal to heatsink	-	29.0	-	mm
		Terminal to terminal	-	23.0	-	
Clearance	d_{Clear}	Terminal to heatsink	-	23.0	-	mm
		Terminal to terminal	-	11.0	-	
Comparative tracking index	CTI		-	200	-	

Parameter	Symbols	Conditions	Value			Unit
			Min	Typ	Max	
Stray inductance module	L_{sCE}		-	35	-	nH
Terminal connection torque	M	Screw M6	3.0	-	6.0	Nm
Mounting torque for module mounting	M	Screw M6	3.0	-	6.0	Nm
Weight	G		-	322	-	g

Typical Characteristics

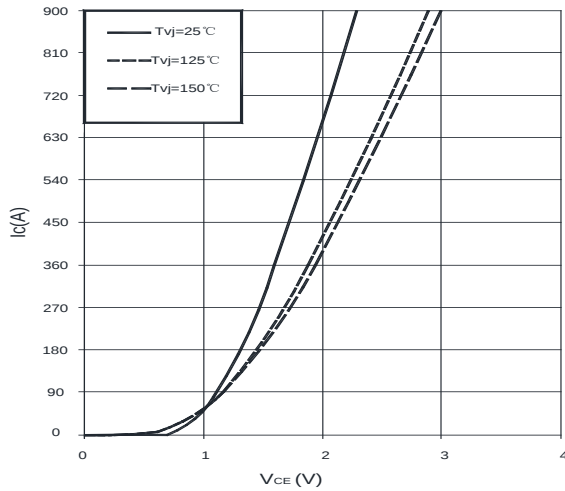


Fig 1. Output characteristic (typical), IGBT, Inverter $I_c = f(V_{CE})$ $V_{GE} = 15V$

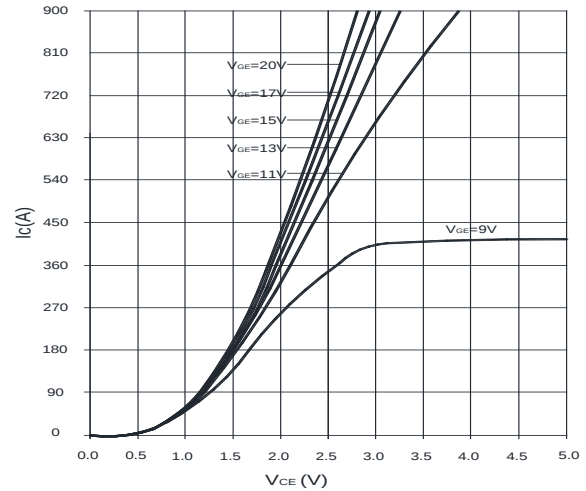


Fig 2. Output characteristic (typical), $I_c = f(V_{CE})$ $T_{vj} = 150^\circ C$

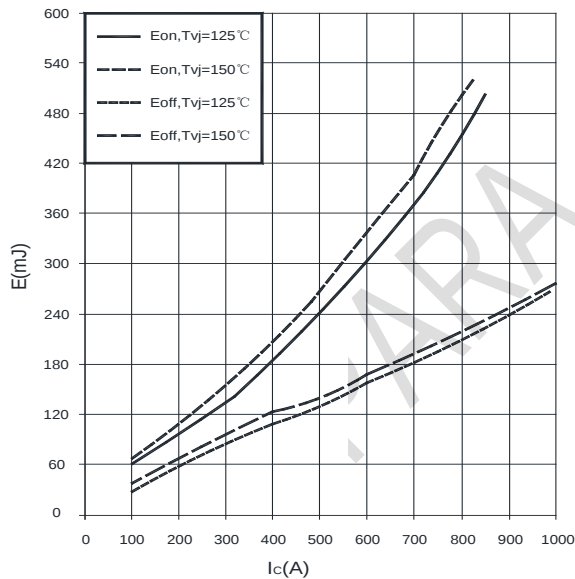


Fig 3. Switching losses (typical), IGBT, Inverter $E = f(I_c)$ $R_{Goff} = 20\Omega$, $R_{Gon} = 20\Omega$, $V_{GE} = \pm 15V$, $V_{CC} = 600V$

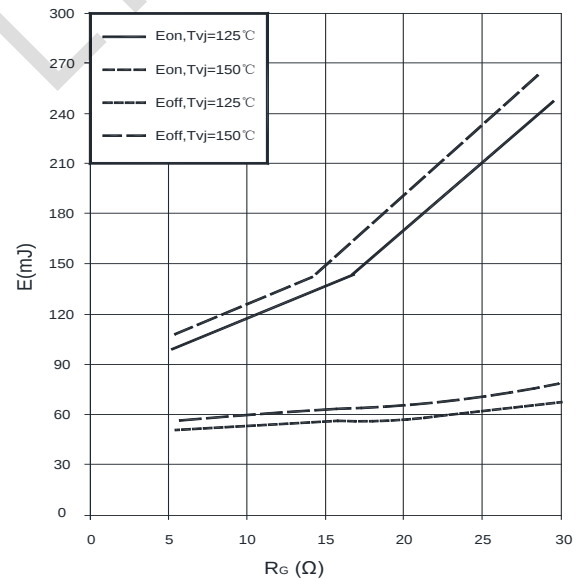


Fig 4. Switching losses (typical), IGBT, Inverter $E = f(R_g)$ $V_{GE} = 15V$, $I_c = 450A$, $V_{CC} = 600V$

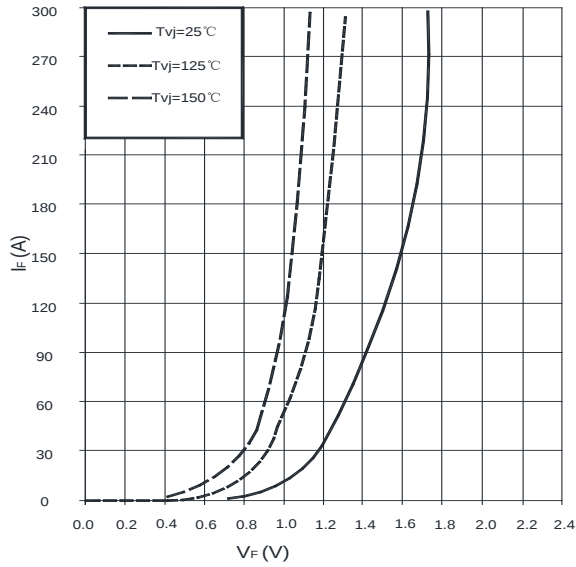


Fig 5. Forward characteristic (typical), Diode, Inverter $I_F = f(V_F)$

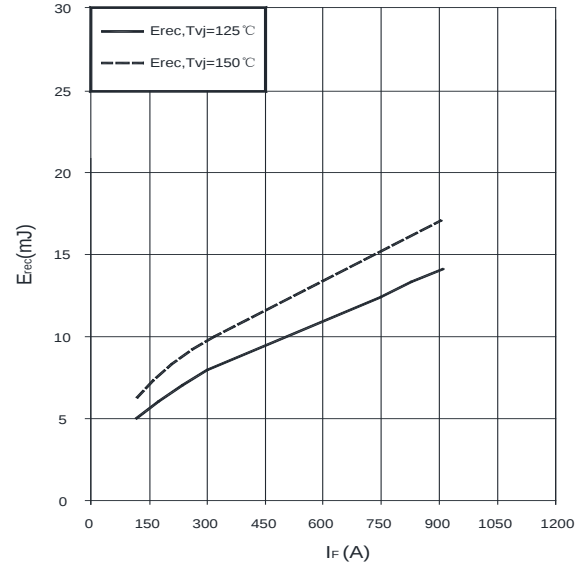


Fig 6. Switching losses (typical), Diode, Inverter $E_{rec} = f(I_F)$ $R_{Gon} = 20\Omega$, $V_{CC} = 600V$

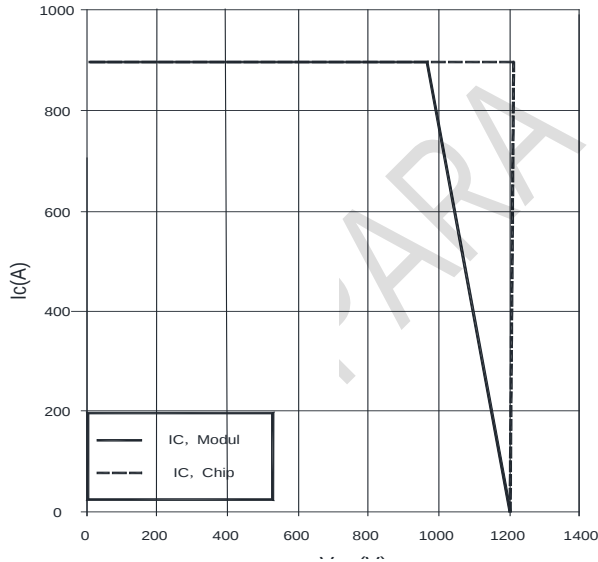
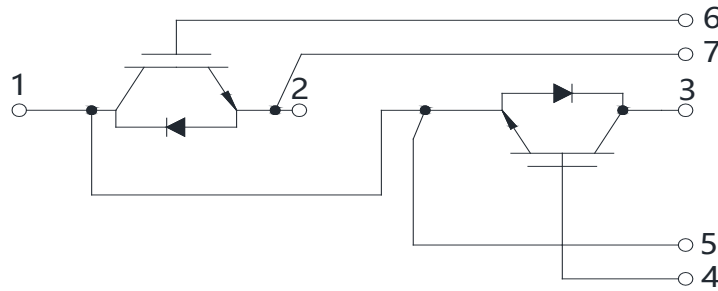
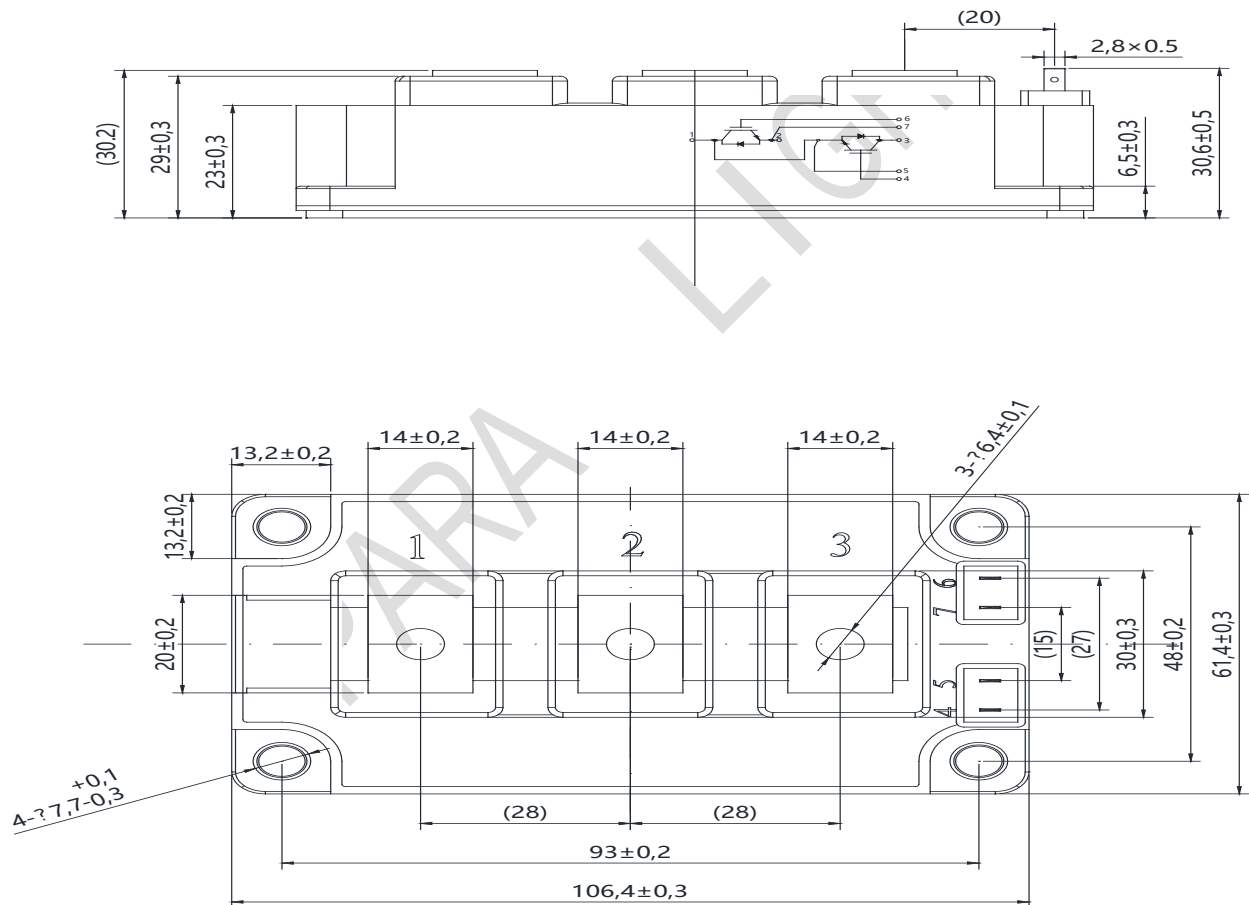


Fig 7. Reverse bias safe operating area (RBSOA), IGBT, Inverter $I_C = f(V_{CE})$ $R_{Goff} = 20\Omega$, $V_{GE} = \pm 15V$, $T_{vj} = 150^\circ C$

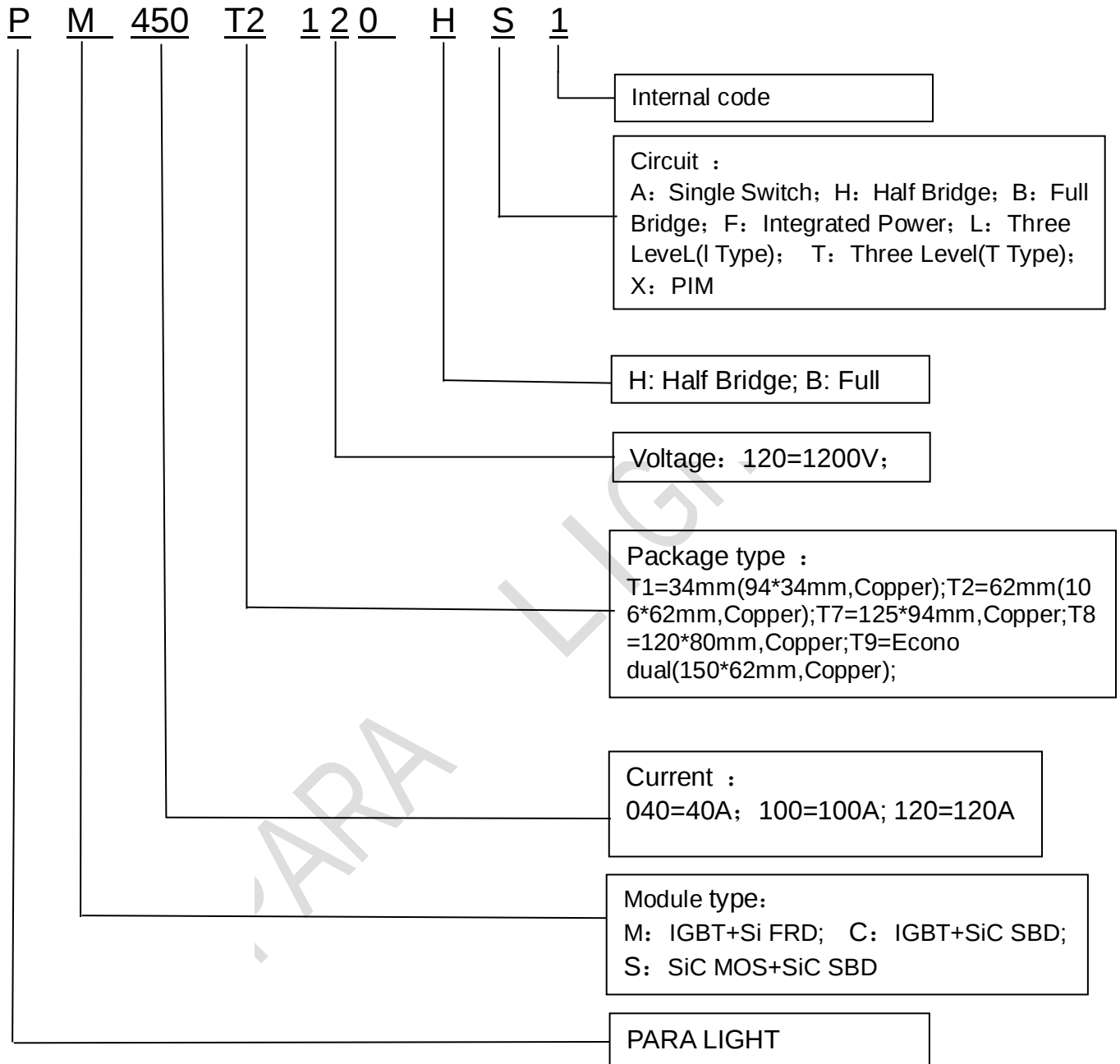
Circuit_diagram_headline



Package outline



PART NO. SYSTEM :



Revision history

Document revision history

Date	Version	Changes
2024.09.28	A / 0	First release.